



The 22nd Asian Test Symposium (ATS'13)

Yilan, Taiwan, 18-21 November 2013

<http://bug.ee.ntu.edu.tw/ATS2013>

Early bird discount by 25 October 2013



行政院國家科學委員會
National Science Council



Program Highlight

Keynote

Test Data Analytics - from Mathematical Tools to Applications

Kwang-Ting (Tim) Cheng, University of California, Santa Barbara

Invited Speeches

New Approaches to Improving Quality and Accelerating Yield Ramp to Meet Process Technology Disruptions

Wu-Tung Cheng, Chief Scientist and Test Research Director, Mentor Graphics

3DIC's System Design Impact and Testing Needs

William Wu Shen, Test Chip Design Verification Division, TSMC

Oral Presentations

Seventeen technical and two industry sessions that cover nearly all aspects of key area in VLSI testing, from 3D-IC to ATPG.

Full-Day and Embedded* Tutorials

Statistical Adaptive Tet Methods Targeting "Zero Defect" IC Quality and Reliability

Adit D. Singh, Auburn University

Testing TSV-Based 3D Stacked ICs

Krishnendu Chakrabarty, Duke University

Data Mining in Test - Principles and Practices*

Li-C Wang, University of California, Santa Barbara

Software Testing*

Farn Wang, National Taiwan University

Vendor Session on New Test Technologies & Roadmap

Mentor Graphics DfT Technologies for High-Quality Cost-Effective Test of SoCs

Cadence Flexible Test Methodologies for Large SoCs

Synopsys New Solutions for Reducing the Time, Effort, and Cost of Quality SoC Testing

General Information

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Program Information

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